

L Number	Hits	Search Text	DE	Time stamp
1	1372	"insulated wire" with coating	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 09:37
2	2	("insulated wire" with coating) and (438/\$).CCLS.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 09:39
3	3	4,360,433.pn.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 09:39
4	433	wire with method with coating with insulating	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 09:40
5	59	(wire with method with coating with insulating) and semiconductor	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 09:45
6	337	copper adj oxide with insulating	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 10:23
7	2	6934195.pn.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:12
8	1	6191391.pn.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:13
9	7	("5530292" "5545922" "5793108" "5817042" "5952725" "5959347" "6102173").PN.	USPAT	2002/05/18 11:12
10	1334	(2577723).CCLS.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:13
11	168	((2577723).CCLS.) and wire adj bond	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:18
14	11	("4862245" "5012323" "5101324" "5191061" "5438224" "5463253" "5471366" "5479051" "5523608" "5539150" "5579208" "5689135").PN.	USPAT	2002/05/18 11:17
15	420	(2577781).CCLS.	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:19
16	7	((2577782).CCLS.) and chip with stacked	USPAT; US-PGPUR; EPO; JPO; DEFWENT; IBM_TDB	2002/05/18 11:20

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65 "insulated wire" and (257/\$).ccls.

USPAT;
US-PGPUB;
EPO; JPO;
DERWENT;
IEM_TDB

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